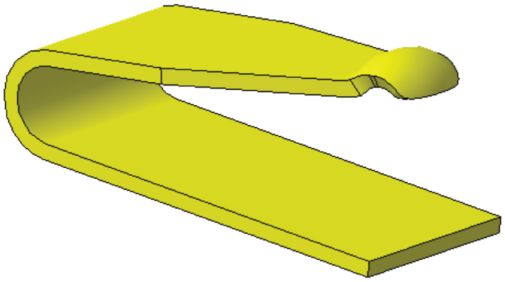
C-Clip Connector

Pulse Part Number W9908



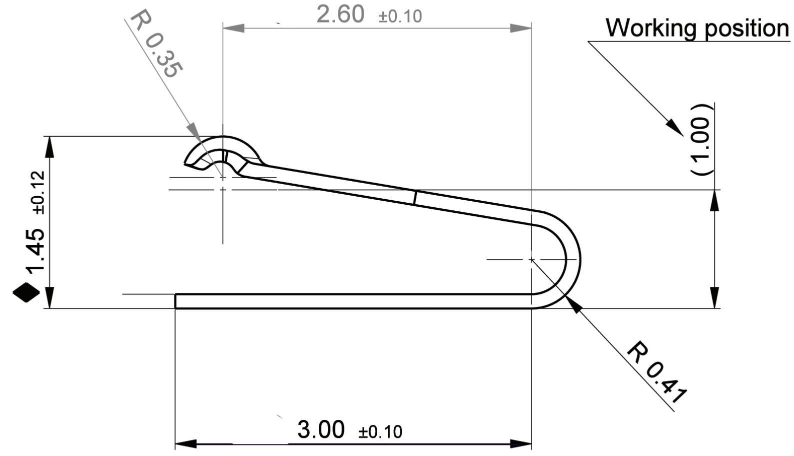
Ideal for board-to-antenna applications
Spring contact for positive connection
Surface mount technology; solder reflowable

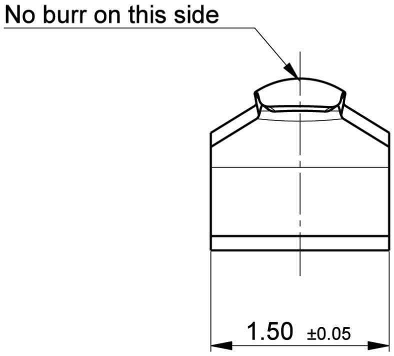
Features

- PWB Footprint 3.2 x 1.7 mm
- Nominal Contact Height 1 mm
- Tape & Reel Packaging
- RoHS Compliant Product

Applications

- Antenna Contacts





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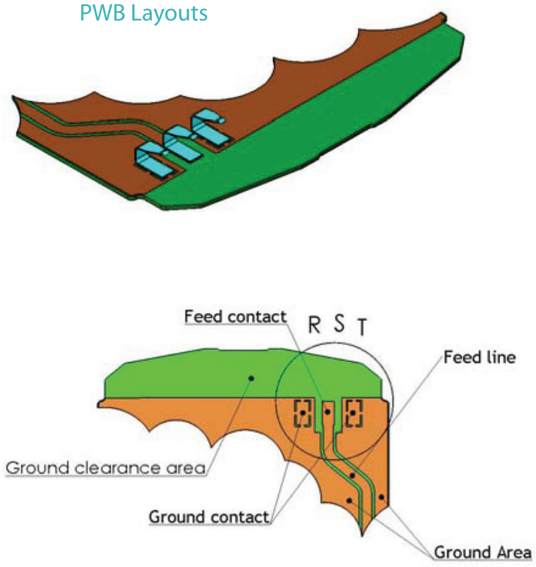
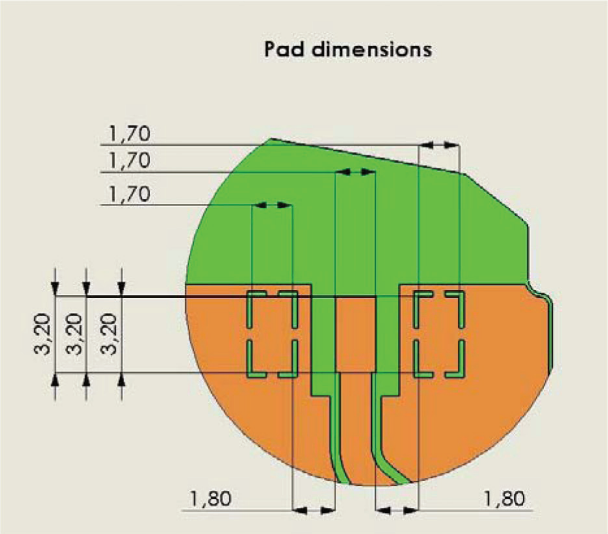
W9908 C-Clip Configuration and Dimensions

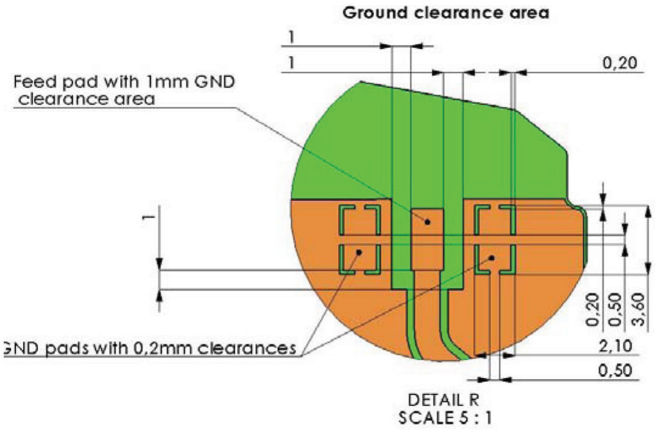
PWB Layouts

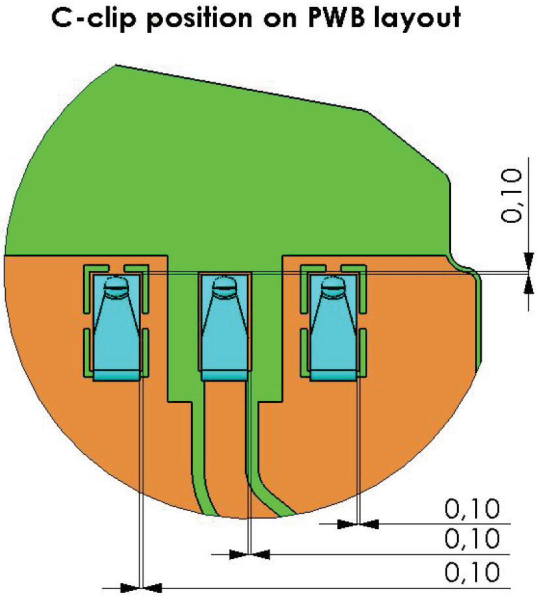


PWB Footprint Dimensions and C-Clip Position for W9908



Ground Clearance Area for W9908 C-Clip





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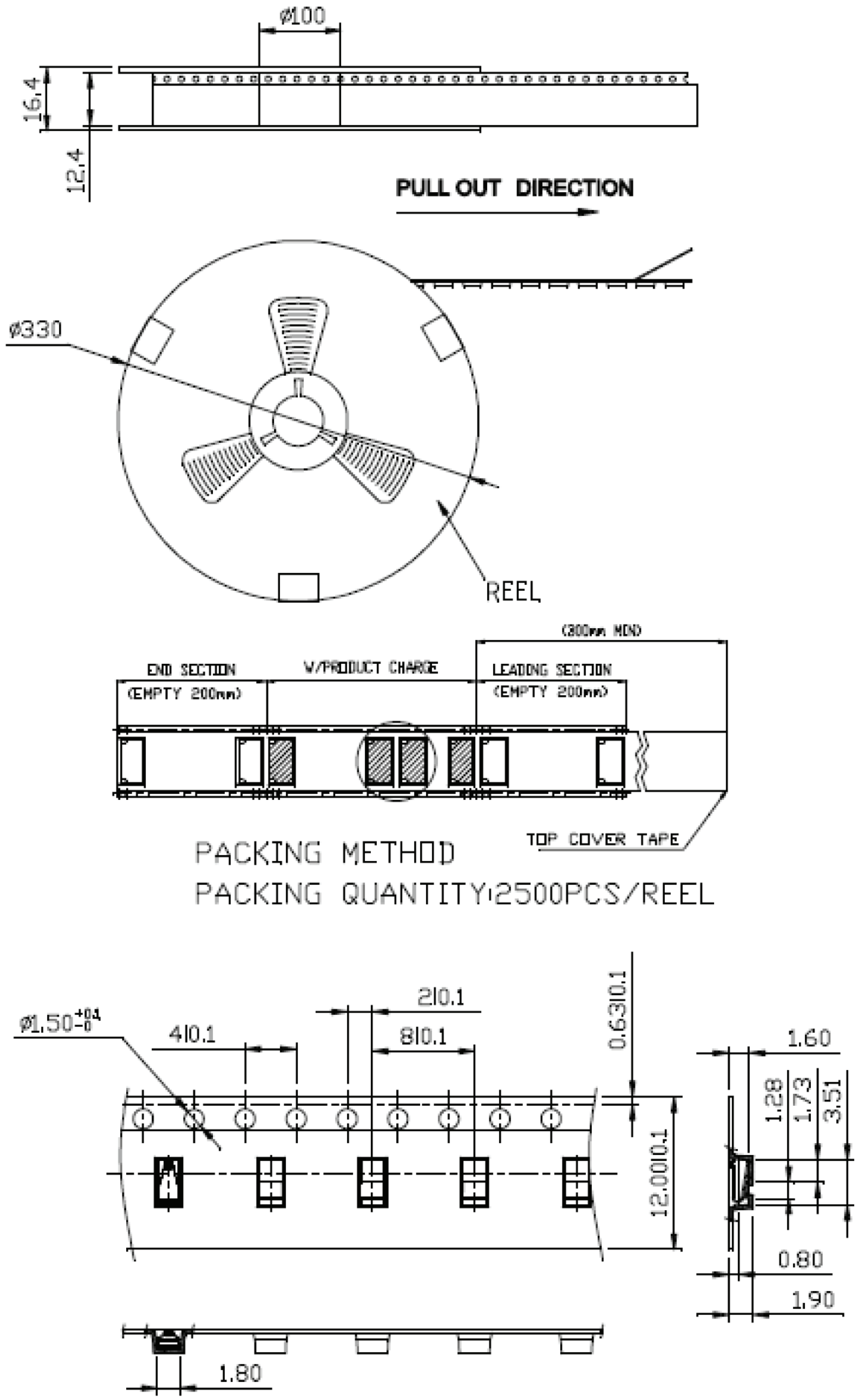
Reel packing:



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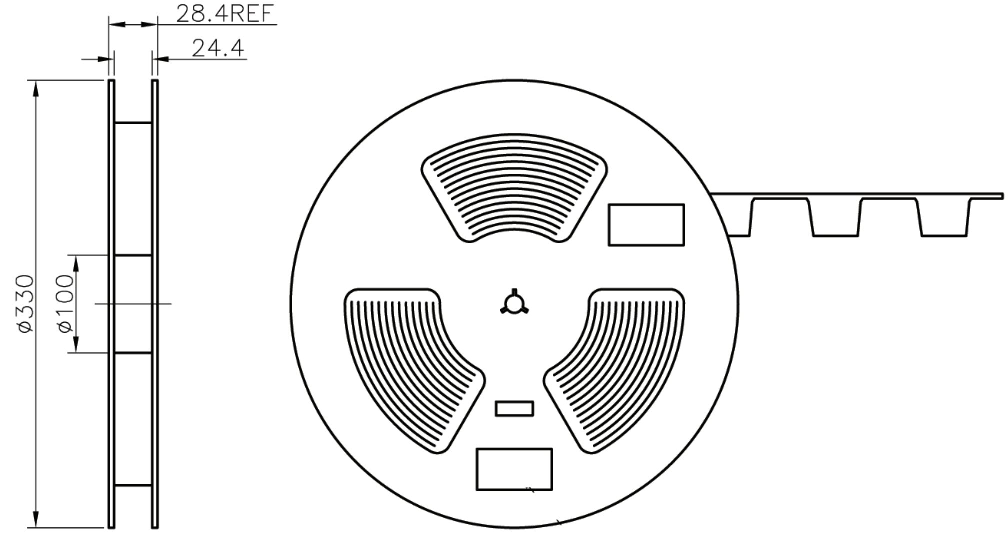

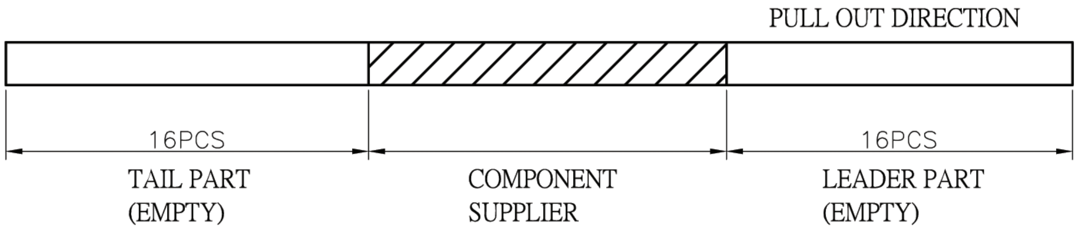

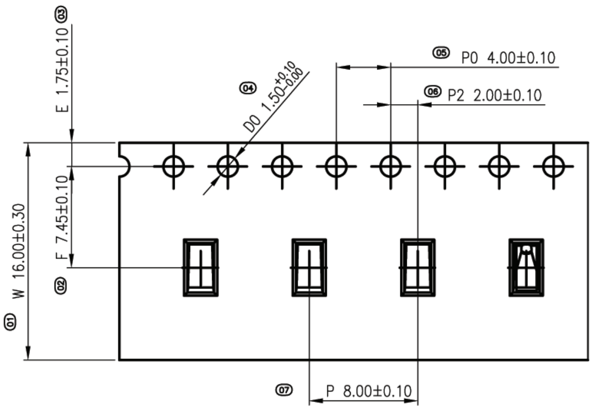

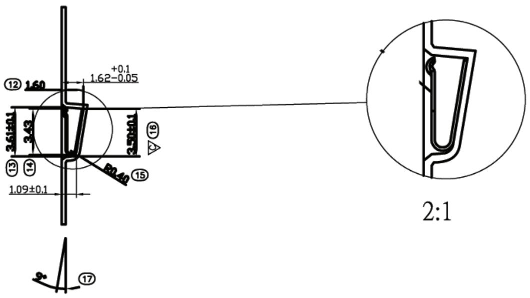

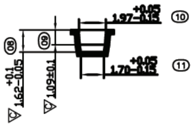

W9908 Connector Soldering

Recommendation for reflow soldering process

Printing stencil thickness 0.15 to 0.25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C.

The temperature profile recommendations for reflow solder process are presented in Figure 1 and 2. The reflow profile presented in Figure 2 describes maximum reflow temperatures.

Figure 1 - Minimum temperature profile recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 30 sec
5	Peak temperature in reflow	230°C for 10 seconds
6	Temperature gradient in cooling	Max -5°C/s